

Title (en)

METHOD FOR PRODUCING BOND PADS ON A PRINTED CIRCUIT

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ANSCHLUSSHÖCKERN AUF EINER LEITERPLATTE

Title (fr)

PROCEDE DE REALISATION DE PLOTS DE CONNEXION SUR UN CIRCUIT IMPRIME

Publication

**EP 1262094 A1 20021204 (FR)**

Application

**EP 01989644 A 20011220**

Priority

- FR 0104117 W 20011220
- FR 0017230 A 20001228

Abstract (en)

[origin: WO02054842A1] The invention concerns a method for producing a chromium coating (4) so that the material of the bond pad (8) remains in a zone totally limited by the chromium coating (4). The invention is applicable to bond pads for electronic components.

IPC 1-7

**H05K 3/34**; **H01L 21/60**; **H01L 21/48**

IPC 8 full level

**H01L 21/48** (2006.01); **H01L 21/60** (2006.01); **H01L 23/485** (2006.01); **H01L 23/498** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP KR US)

**H01L 21/4853** (2013.01 - EP US); **H01L 23/49816** (2013.01 - EP US); **H01L 24/05** (2013.01 - EP US); **H01L 24/11** (2013.01 - EP US); **H01L 24/13** (2013.01 - EP US); **H05K 3/3452** (2013.01 - EP US); **H05K 3/3473** (2013.01 - EP US); **H05K 3/40** (2013.01 - KR); **H01L 24/03** (2013.01 - EP); **H01L 2224/02166** (2013.01 - EP US); **H01L 2224/05001** (2013.01 - EP US); **H01L 2224/05016** (2013.01 - EP US); **H01L 2224/05018** (2013.01 - EP US); **H01L 2224/05022** (2013.01 - EP US); **H01L 2224/05023** (2013.01 - EP US); **H01L 2224/05571** (2013.01 - EP US); **H01L 2224/05576** (2013.01 - EP US); **H01L 2224/05671** (2013.01 - EP US); **H01L 2224/10126** (2013.01 - EP US); **H01L 2224/1147** (2013.01 - EP US); **H01L 2224/13099** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/01024** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01058** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H05K 2201/2081** (2013.01 - EP US); **H05K 2203/0361** (2013.01 - EP US); **H05K 2203/043** (2013.01 - EP US); **H05K 2203/0542** (2013.01 - EP US)

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